DP-309697 (DEL01 P-447)

WAFER APPLIED THERMALLY CONDUCTIVE INTERPOSER

Abstract of the Disclosure

A thermally conductive film is attached to an integrated circuit (IC) wafer through a number of steps. Initially, a thermally conductive film is positioned on a first side of a block. Next, an IC wafer that includes a plurality of chips is positioned with its non-active side in contact with the film. Then, a first surface of an elastomer pad is positioned in contact with an active side of the wafer. Next, a predetermined pressure is applied between a second side of the block that is opposite the first side and a second surface of the elastomer pad that is opposite the first surface. Finally, the film, the block, the wafer and the elastomer pad are heated to a predetermined temperature for a predetermined time while a predetermined pressure is applied to bond the film to the wafer without bonding the film to the block.